

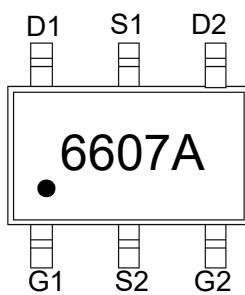


Features

- Trench Power LV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching

Application

- DC/DC converter
- Load switch
- LCD display inverter



6607A : Device code

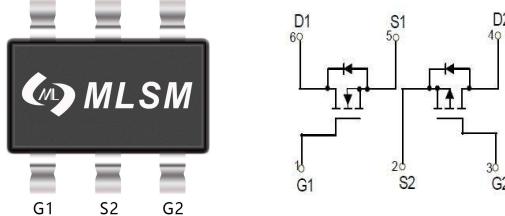
Marking and pin assignment

Product Summary

V_{DS}	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
20V	27mΩ@4.5V	6A
	40mΩ@2.5V	
-20V	45mΩ@-4.5V	-5A
	65mΩ@-2.5V	



SOT-23-6L top view



Schematic diagram



Halogen-Free

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Unit
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Common Ratings (TC=25°C Unless Otherwise Noted)

V_{DS}	Drain-Source Breakdown Voltage	20	-20	V
V_{GS}	Gate-Source Voltage	±10	±10	V
T_J	Maximum Junction Temperature	150	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
I_S	Diode Continuous Forward Current	Tc=25°C 6	-5	A

Mounted on Large Heat Sink

I_{DM}	Pulse Drain Current Tested	Tc=25°C 24	-20	A
I_D	Continuous Drain Current	Tc=25°C 6	-5	A
P_D	Maximum Power Dissipation	Tc=25°C 0.35	0.35	W
$R_{θJA}$	Thermal Resistance Junction-Ambient	357	357	°C/W

Ordering Information (Example)

Type	Package	Marking	Minimum Package(pcs)	Inner Box Quantity(pcs)	Outer Carton Quantity(pcs)	Delivery Mode
MLSL6607A	SOT-23-6L	6607A	3,000	45,000	180,000	7"reel



N-Ch Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
BV _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =6.0A	--	20	27	mΩ
		V _{GS} =2.5V, I _D =5.5A	--	28	40	mΩ

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHz	--	378	--	pF
C _{oss}	Output Capacitance		--	74	--	pF
C _{RSS}	Reverse Transfer Capacitance		--	58	--	pF

Switching Characteristics

Q _g	Total Gate Charge	V _{DS} =10V, I _D =6A, V _{GS} =4.5V	--	6.08	--	nC
Q _{gs}	Gate Source Charge		--	1.07	--	nC
Q _{gd}	Gate Drain Charge		--	1.95	--	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =10V, R _L =1Ω, V _{GS} =4.5V, R _G =3Ω	--	4.2	--	nS
t _r	Turn-on Rise Time		--	19.8	--	nS
t _{d(off)}	Turn-Off Delay Time		--	22.6	--	nS
t _f	Turn-Off Fall Time		--	23.2	--	nS

Source-Drain Diode Characteristics

V _{SD}	Forward on voltage	T _J =25°C, I _S =6A	--	--	1.2	V
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P-Ch Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
BV _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±10V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.6	-1.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-5.0A	--	32	45	mΩ
		V _{GS} =-2.5V, I _D =-4.5A	--	45	65	mΩ

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

C _{ISS}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz	--	1015	--	pF
C _{OSS}	Output Capacitance		--	138	--	pF
C _{RSS}	Reverse Transfer Capacitance		--	105	--	pF

Switching Characteristics

Q _g	Total Gate Charge	V _{DS} =-10V, I _D =-5A, V _{GS} =-10V	--	11.3	--	nC
Q _{gs}	Gate Source Charge		--	2.3	--	nC
Q _{gd}	Gate Drain Charge		--	2.4	--	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =-10V, I _D =-5A, V _{GS} =-10V, R _G =2.5Ω	--	8.5	--	nS
t _r	Turn-on Rise Time		--	35.5	--	nS
t _{d(off)}	Turn-Off Delay Time		--	78	--	nS
t _f	Turn-Off Fall Time		--	58	--	nS

Source-Drain Diode Characteristics

V _{SD}	Forward on voltage	T _J =25°C, I _S =-5A	--	--	-1.2	V
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N-Channel Typical Operating Characteristics

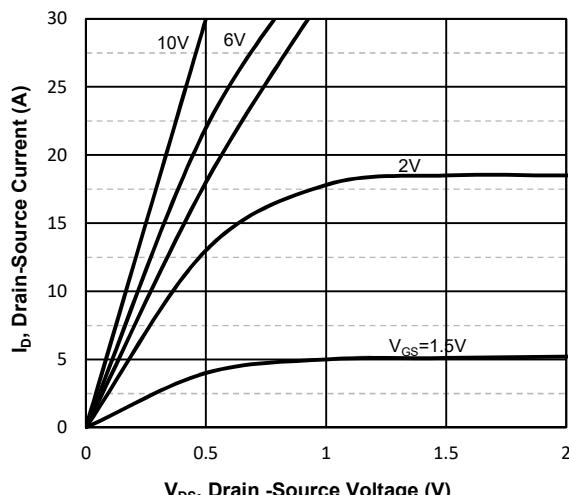


Fig1. Typical Output Characteristics

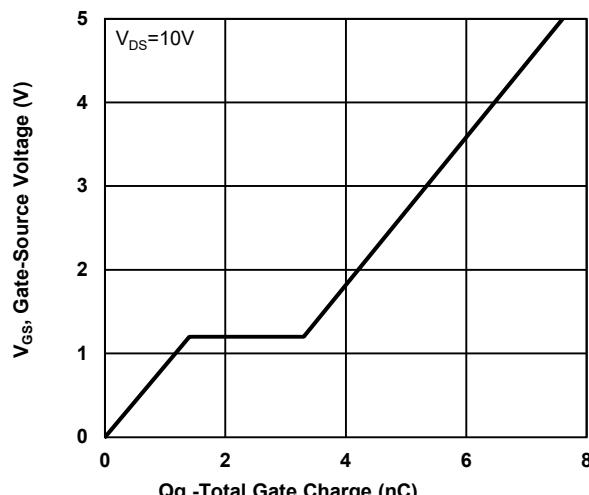


Fig2. Typical Gate Charge Vs. Gate-Source Voltage

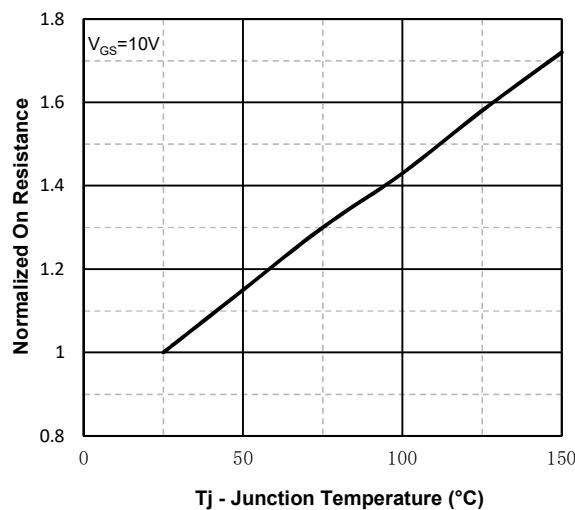


Fig3. Normalized On-Resistance Vs. Temperature

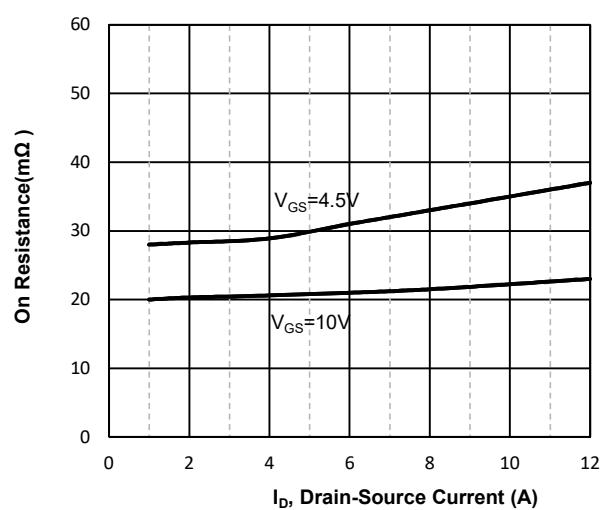


Fig4. On-Resistance Vs. Drain-Source Current

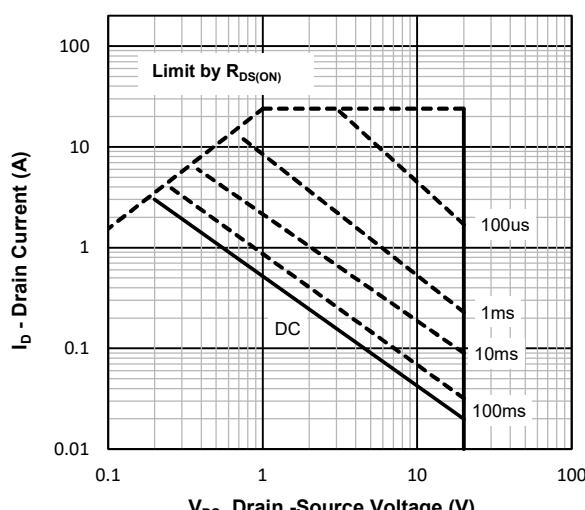


Fig5. Maximum Safe Operating Area

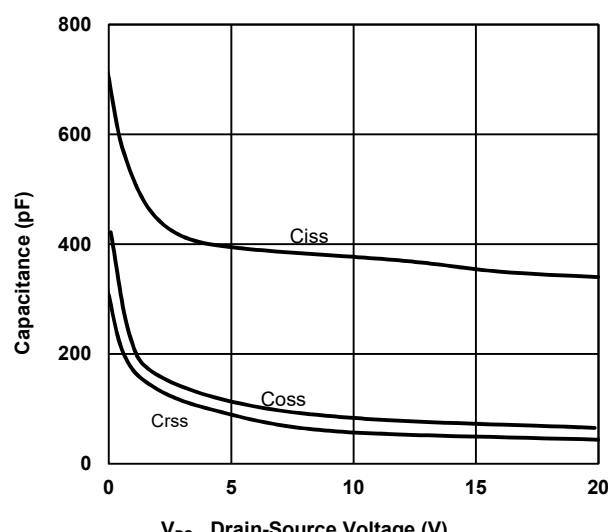


Fig6. Typical Capacitance Vs. Drain-Source Voltage

P-Channel Typical Operating Characteristics

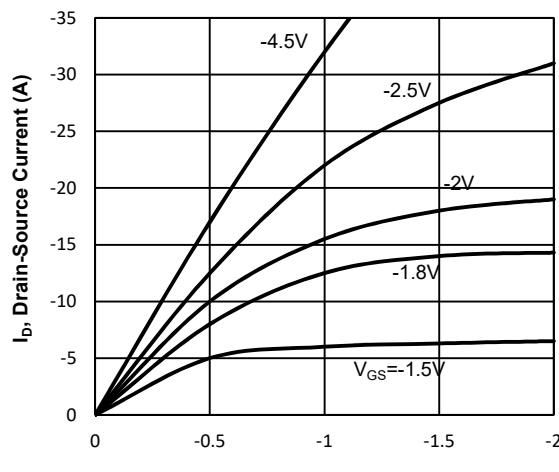


Fig7. Typical Output Characteristics
 V_{DS} , Drain -Source Voltage (V)
 V_{GS} = -1.5V

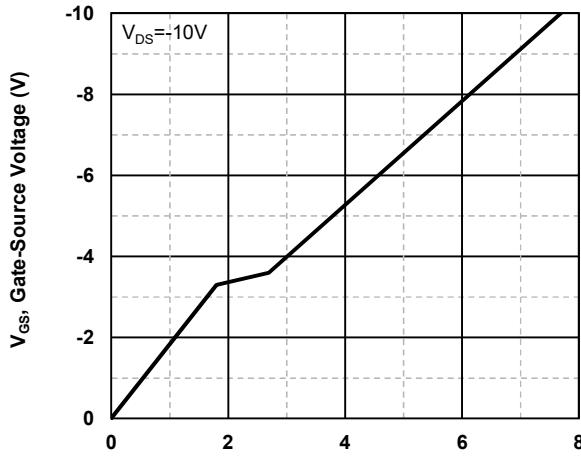


Fig8. Typical Gate Charge Vs.Gate-Source Voltage
 V_{DS} = 10V
 Q_g -Total Gate Charge (nC)

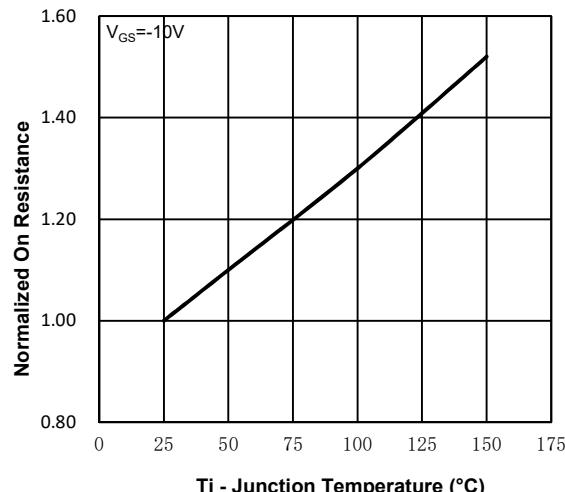


Fig9. Normalized On-Resistance Vs. Temperature
 V_{GS} = -10V
 T_j - Junction Temperature (°C)

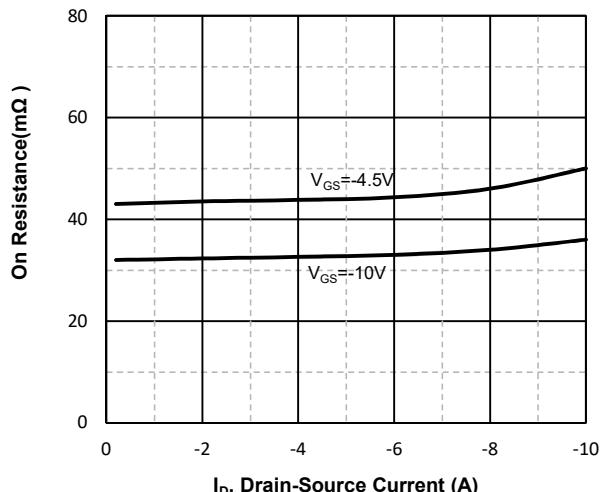


Fig10. On-Resistance Vs. Drain-Source Current
 V_{GS} = -4.5V
 V_{GS} = -10V
 I_D , Drain-Source Current (A)

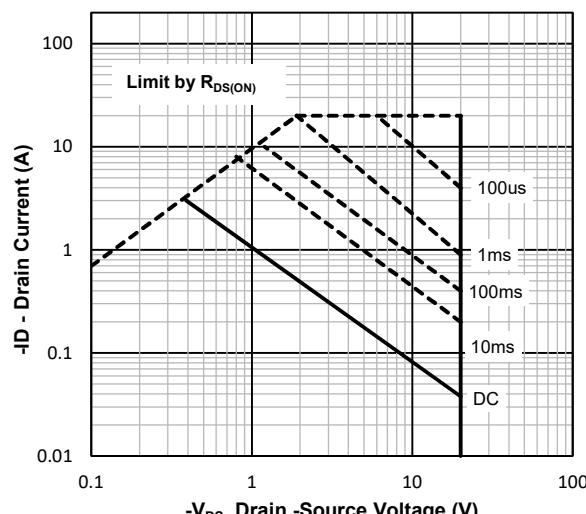


Fig11. Maximum Safe Operating Area
 V_{DS} , Drain -Source Voltage (V)
 I_D - Drain Current (A)

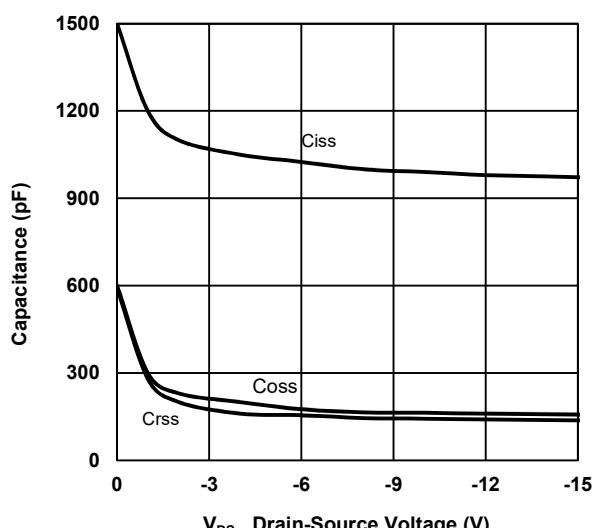
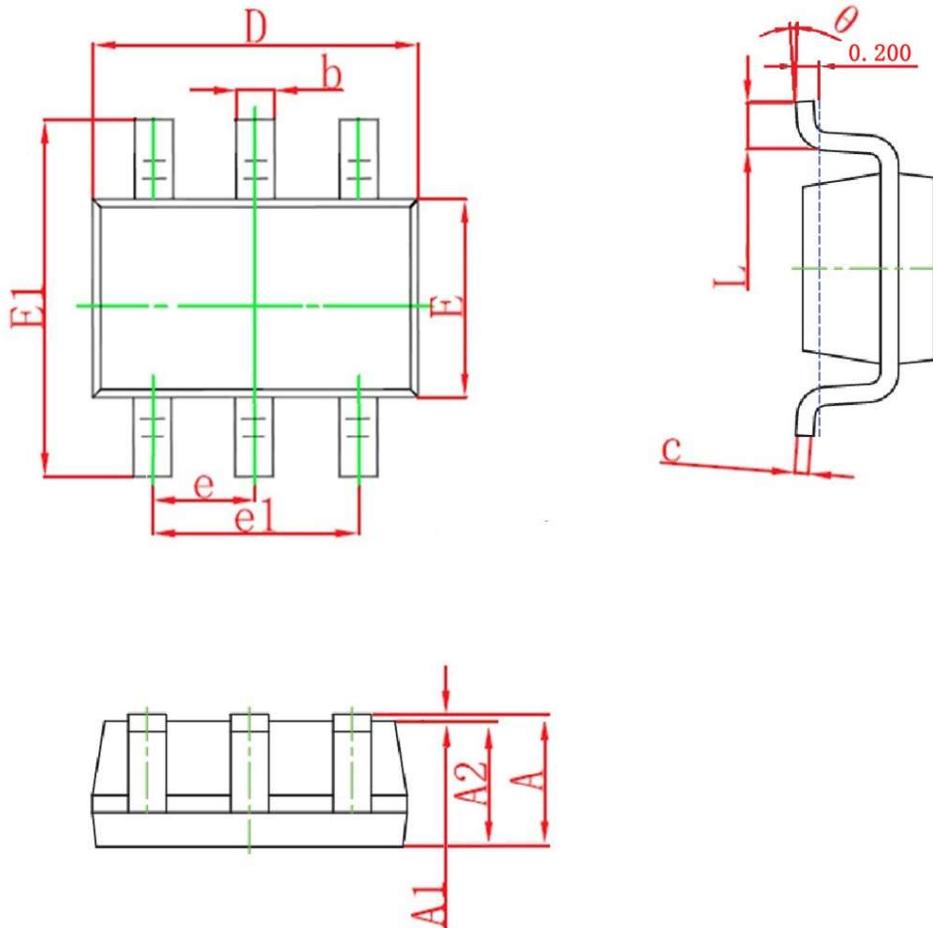


Fig12. Typical Capacitance Vs.Drain-Source Voltage
 V_{DS} , Drain-Source Voltage (V)
 C_{iss} , C_{oss} , C_{rss} - Capacitance (pF)



SOT-23-6L Package information



Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.039	0.047
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.600	3.000	0.102	0.118
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
K	0°	8°	0°	8°